

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



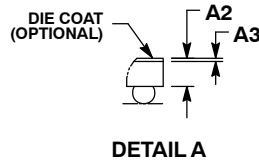
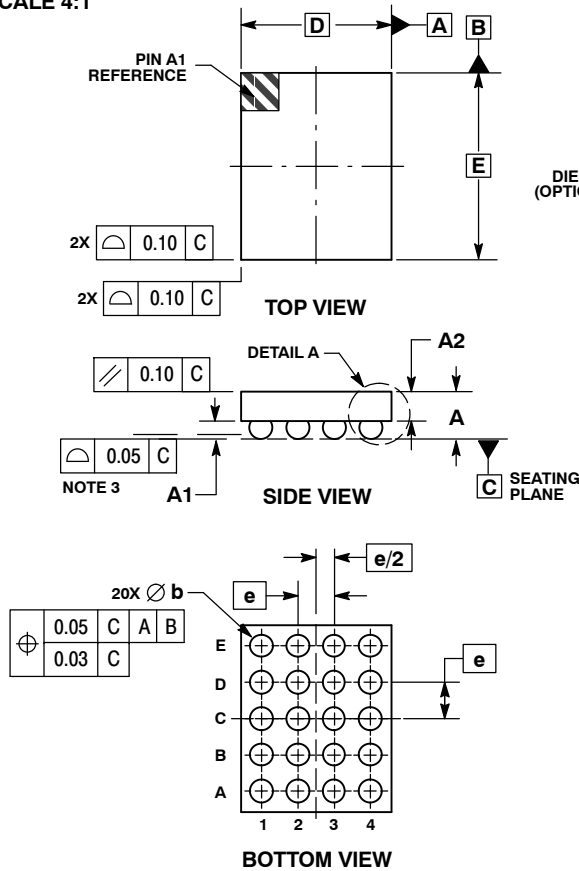
### WLCSP20, 1.62x2.02

CASE 568AG  
ISSUE D

DATE 13 AUG 2013



SCALE 4:1

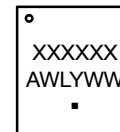


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.33	0.39
A3	0.02	0.04
b	0.24	0.28
D	1.62 BSC	
E	2.02 BSC	
e	0.40 BSC	

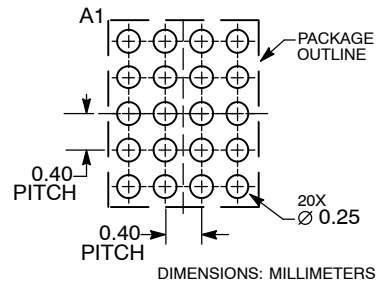
**GENERIC MARKING DIAGRAM\***



- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	WLCSP20, 1.62X2.02	<b>PAGE 1 OF 2</b>

